

ABSTRACT

A leadframe packaging apparatus including a die, at least two separated die pads each connected to a corresponding voltage level thereof, a plurality of leadfingers, and at least one passive component having two ends each connected to one of the two separated die pads. A packaging method for the leadframe apparatus is further provided, wherein the method prepares at least one die pad disposed in separated fashion, integrated circuit dies adhered to separated die pads, and passive components having two ends connected with separated die pads before forming the molding compound, thereby placing the passive components within the molding compound.